INTEGRATED LIGHT SOURCE INTELLIGENT CONTROL
OF CHIP-ON-TOP SMD TYPE LED
Model: SK6812B-3535

1. Product Overview :

SK6812B-3535 is a smart **LED** control circuit and light emitting circuit in one controlled **LED** source, which has the shape of a 3535 **LED** chip. Each lighting element is a pixel, and the intensities of the pixels are contained within the intelligent digital interface input. The output is driven by patented **PWM** technology, which effectively guarantees high consistency of the color of the pixels. The control circuit consists of a signal shaping amplification circuit, a built-in constant current circuit, and a high precision **RC** oscillator.

The data protocol being used is unipolar NRZ communication mode. The 24-bit data is transmitted from the controller to DIN of the first element, and if it is accepted it is extracted pixel to pixel. After an internal data latch, the remaining data is passed through the internal amplification circuit and sent out on the DO port to the remaining pixels. The pixel is reset after the end of DIN. Using automatic shaping forwarding technology makes the number of cascaded pixels without signal transmission only limited by signal transmission speed.

The **LED** has a low driving voltage (which allows for environmental protection and energy saving), high brightness, scattering angle, good consistency, low power, and long life. The control circuit is integrated in the **LED** above.

2. Main Application Field:

● Full color **LED** string light, **LED** full color module, **LED** super hard and soft lights, **LED** guardrail tube, **LED** appearance / scene lighting

● **LED** point light, **LED** pixel screen, **LED** shaped screen, a variety of electronic products, electrical equipment etc..
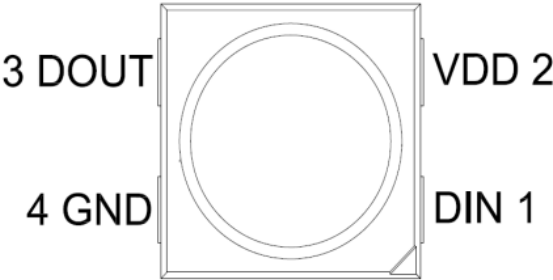
3. Description:

● Top **SMD** internal integrated high quality external control line serial cascade constant current IC;

● control circuit and the **RGB** chip in **SMD** 3535 components, to form a complete control of pixel, color mixing uniformity and consistency;

●built-in data shaping circuit, a pixel signal is received after wave shaping and output waveform distortion will not guarantee a line;

●The built-in power on reset and reset circuit, the power does not work;

●gray level adjusting circuit (256 level gray scale adjustable);

● red drive special treatment, color balance;

● line data transmission;

● plastic forward strengthening technology, the transmission distance between two points over 10M;

●Using a typical data transmission frequency of 800 Kbps, when the refresh rate of 30 frames per sec

4. Mechanical Dimensions:

Notes:
1. All dimensions are in millimeters.
2. Tolerance is ±0.1mm unless otherwise noted
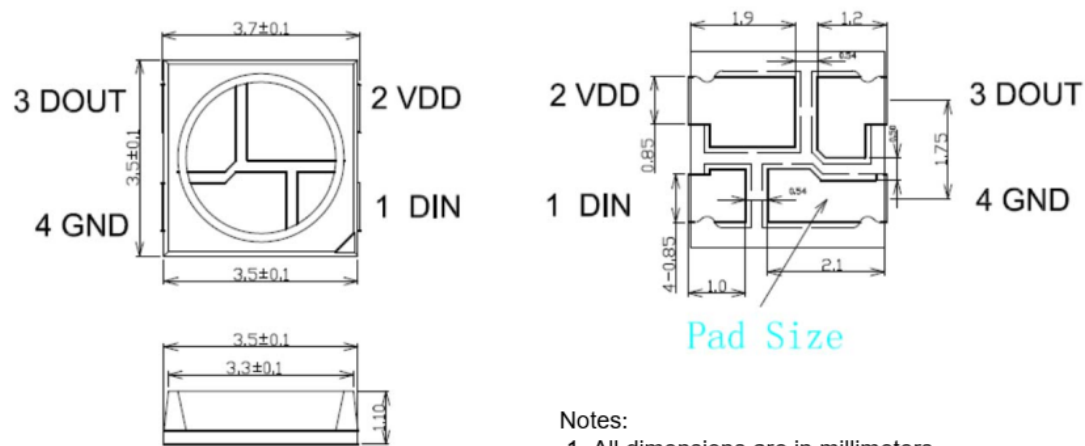
5. PIN configuration and solder pads

NO.	Symbol	Function description
1	DIN	Control data signal input
2	VDD	Power supply LED
3	DOUT	Control data signal output
4	GND	Ground

6. General Information

SK6812B-3535

SK6812B : The default is RGB chips with IC integration

Color	SK6812B-3535 RGB LED Series		
	Wavelength	MCD	Lumen
Red	620-623nm	400-700mcd	1.0-2.0lm
Green	520-530nm	1000-1500mcd	3.0-4.0lm
Blue	460-470nm	200-400mcd	0.5-1.0lm

7. Absolute Maximum Ratings（Ta=25℃,VSS=0V）:

Parameter	Symbol	Range	Unit
Power supply voltage	VDD	+3.5～+5.5	V
Logic input voltage	V_{IN}	-0.5～VDD+0.5	V
Working temperature	Topt	-40~+85	℃
Storage temperature	Tstg	-50~+150	℃
ESD pressure	V_{ESD}	4K	V

8. The electrical parameters (unless otherwise specified, TA=-20 ~ +70 ℃, VDD=4.5 ~ 5.5V, VSS=0V):

Parmeter	Symbol	Min	Typical	Max	Unit	Test conditions
The chip supply voltage	VDD	---	5.2	---	V	---
R/G/B port pressure	VDS,MAX	---	---	26	V	---
DOUT drive capability	IDOH	---	49	---	mA	DOUT conect ground, the maximum drive current
	IDOL	---	-50	---	mA	DOUT conect +, the largest current
The signal input flip threshold	VIH	3.4	---	---	V	VDD=5.0V
	VIL	---	---	1.6	V	
The frequency of PWM	FPWM	---	1.2	---	KHZ	---
Static power consumption	IDD	---	1	---	mA	---

9. The dynamic parameters (Ta=25 ℃):

Parameter	Symbol	Min	Typical	Max	Unit	Test conditions
The speed of data transmission	fDIN	---	800	---	KHZ	The duty ratio of 67% (data 1)
DOUT transmission delay	TPLH	---	---	500	ns	DIN→DOUT
	TPHL	---	---	500	ns	
IOUT Rise/Drop Time	Tr	---	100	---	ns	VDS=1.5 IOUT=13mA
	Tf	---	100	---	ns	
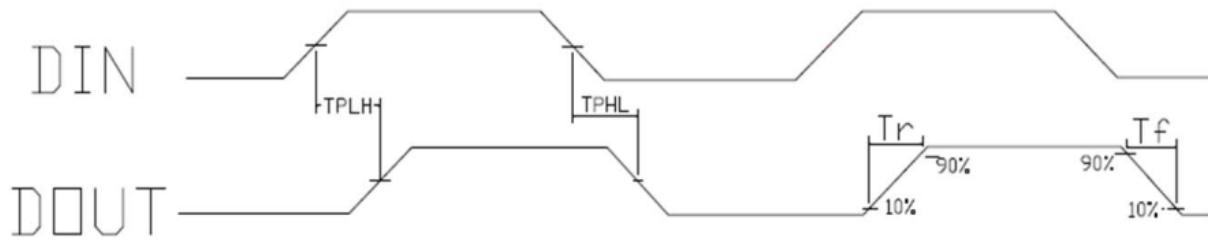
10. The data transmission time (TH+TL=1.25μs±600ns):

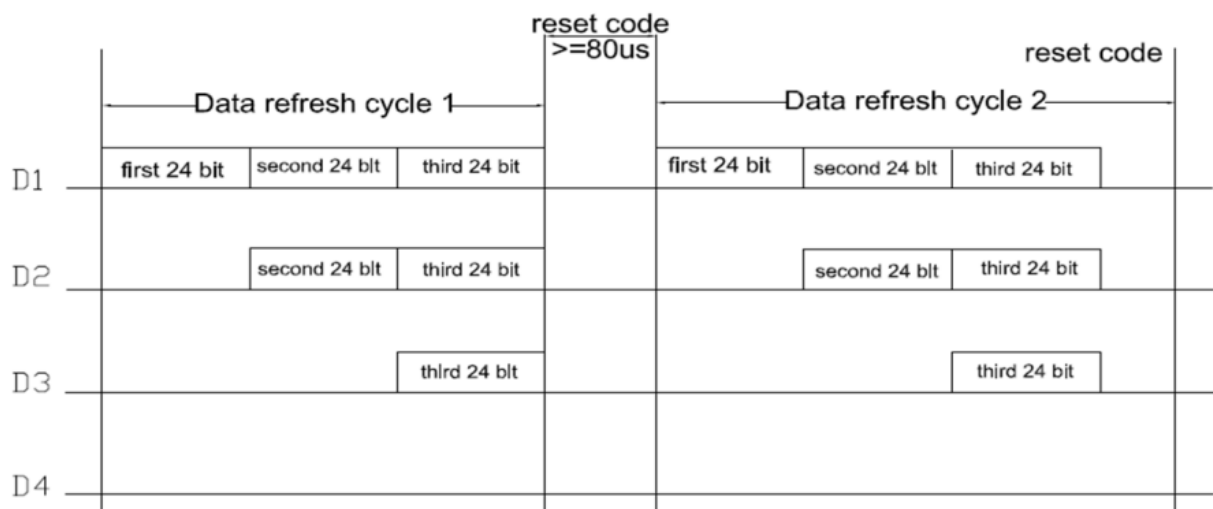|			
T0H	0 code, high level time	0.3μs	±0.15μs
T0L	0 code, low level time	0.9μs	±0.15μs
T1H	1 code, high level time	0.6μs	±0.15μs
T1L	1 code, low level time	0.6μs	±0.15μs
Trst	Reset code，low level time	80μs	

11. Timing waveform:

Input code:
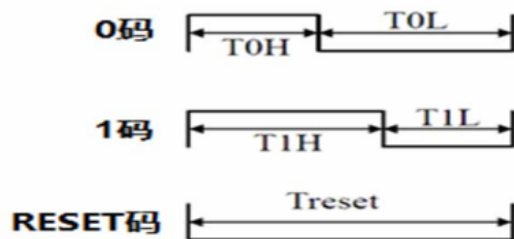
Connection mode:
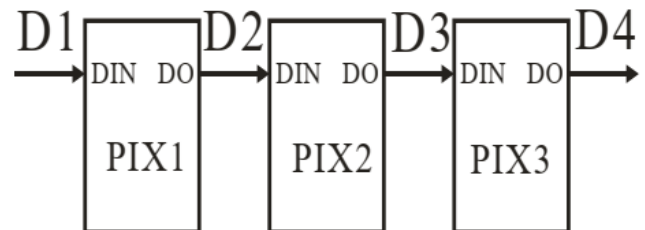
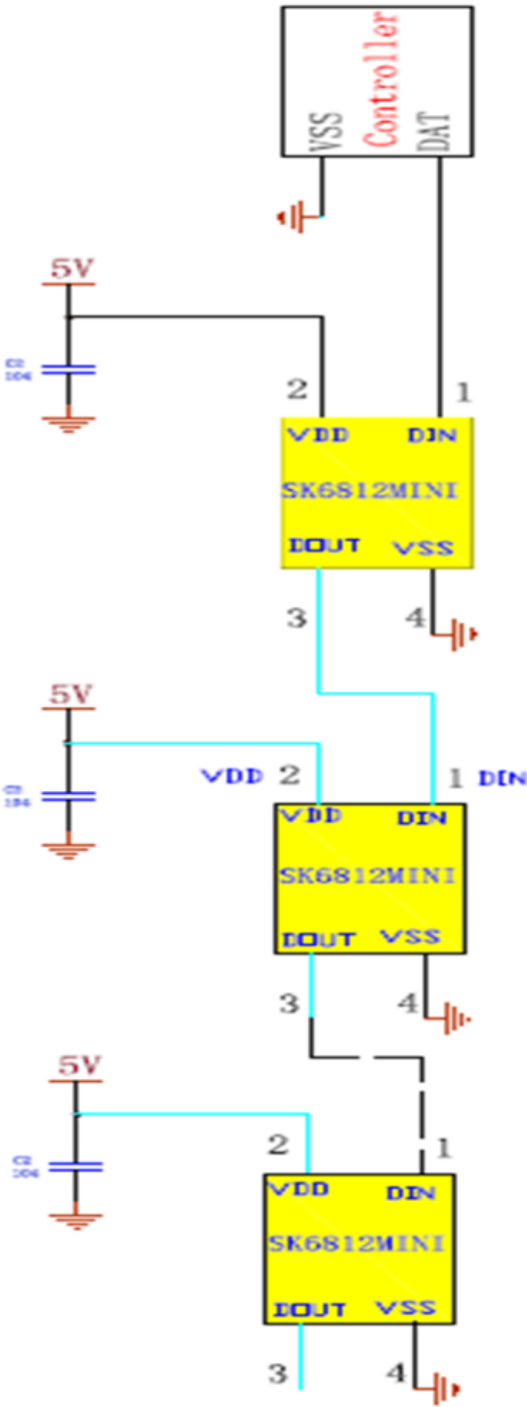## 12. The method of data transmission:

Note: the D1 sends data for MCU, D2, D3, D4 for data forwarding automatic shaping cascade circuit.

13. The data structure of 24bit:

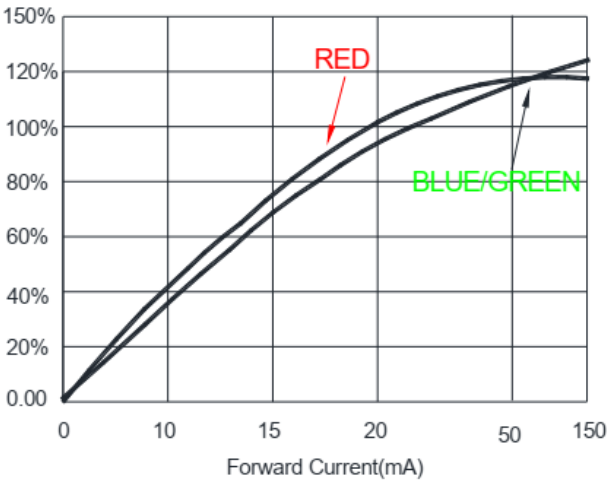| G7	G6	G5	G4	G3	G2	G1	G0	R7	R6	R5	R4
R3	R2	R1	R0	B7	B6	B5	B4	B3	B2	B1	B0

Note: high starting, in order to send data (G7 - G6 - ....B0)
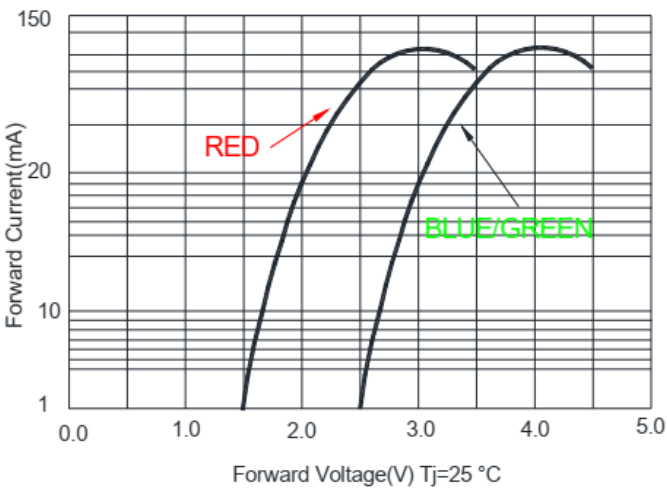
14. The typical application circuit:
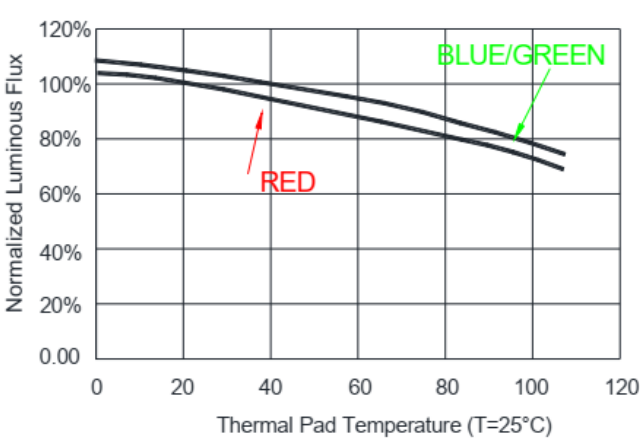
15. Standard LED Performance Graph:

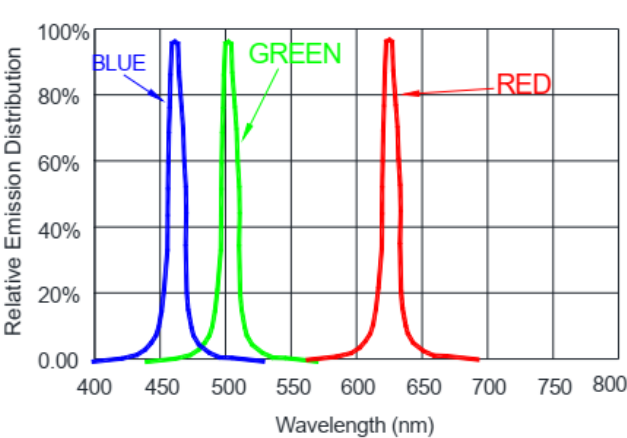### Typical Relative Luminous Flux vs. Forward Current

RED

BLUE/GREEN

Forward Current(mA)

Forward Voltage vs. Forward Current

RED

BLUE/GREEN

Forward Voltage(V) Tj=25 °C

Thermal Pad Temperature vs. Relative Light Output

BLUE/GREEN

RED

Thermal Pad Temperature (T=25°C)

Wavelength Characteristics

BLUE

GREEN

RED

Wavelength (nm)

Thermal Pad Temperature vs. Forward Current

BLUE/GREEN

RED

Thermal Pad Temperature (°C)
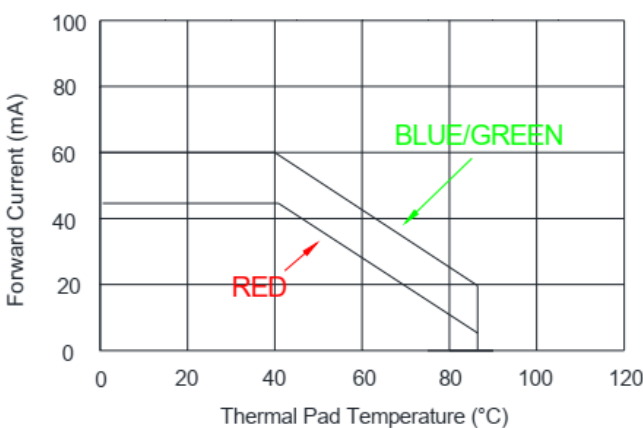
Typical Radiation Pattern   120°

0

30°

60°

90°

90 75 60 45 30 15 0   0.2 0.4 0.6 0.8 1.0

Radiation Angle
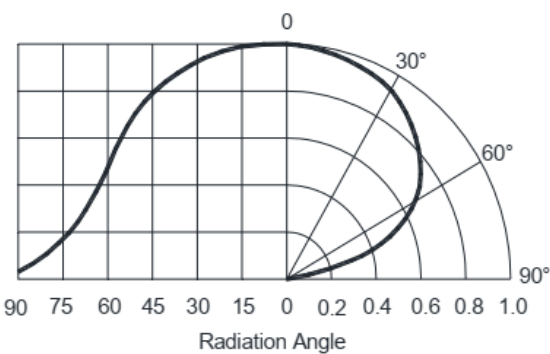
16. Packaging Standard:
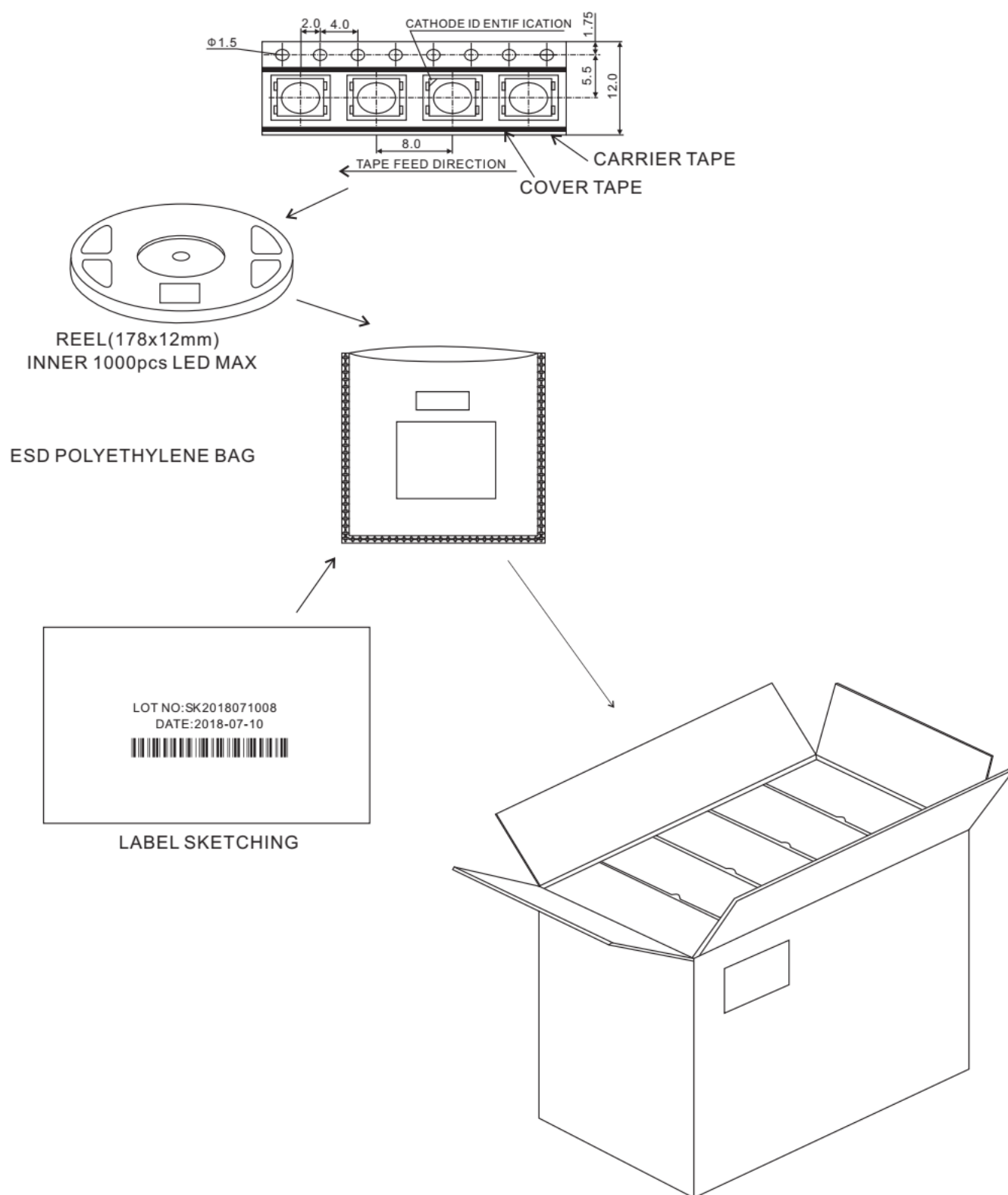
The reel pack is applied in SMD LED. The LEDs are packed in cardboard boxes after packaging in normal or anti-electrostatic bags. cardboard boxes will be used to protect the LEDs from mechanical shocks during transportation. The boxes are not water resistant and therefore must be kept away from water and moisture.

17. Attention

17.1 Dust & Cleaning

The LED use silicone glue to package the 3535 Surface, silicone surface can protect optical properties and improved anti-aging properties. However, silicone is a softer material and prone to attract dust. While a minimal amount of dust and debris on the LED will not cause significant reduction in illumination.We still need to avoid dust falling on the LED surface. After open the bags it must be used immediately.

When you use trichloroethylene or acetone to clean, sometimes the LED surface will dissolve.

Avoid using organic solvent, it is recommended that isopropyl be used as a solvent for cleaning the LEDs.When using other solvents, it should be confirmed beforehand whether the solvents will dissolve thepackage and the resin of not.

Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence as ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power. Baking time and assembled condition.

Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

17.2 Dehumidification

This smart led are moisture sensitive components, In IPC/JEDEC J-STD-020 MSL Level is 6. **No Matter the Package bag is open or not ,The LED must do dehumidification in the oven for 24 hours at 70 degree before use and used within 4 hours, otherwise it need to be dehumidified again**

17.3 Reflow Soldering Characteristics

In our Test, manufacturer comfirm those smart led are compatible with JEDEC J-STD-020C,Customers are required to follow the soldering temperature profile recommended by the solder paste manufacturer used.

Please note that this general guideline may not apply to all PCB design and reflow soldering equipment configurations.
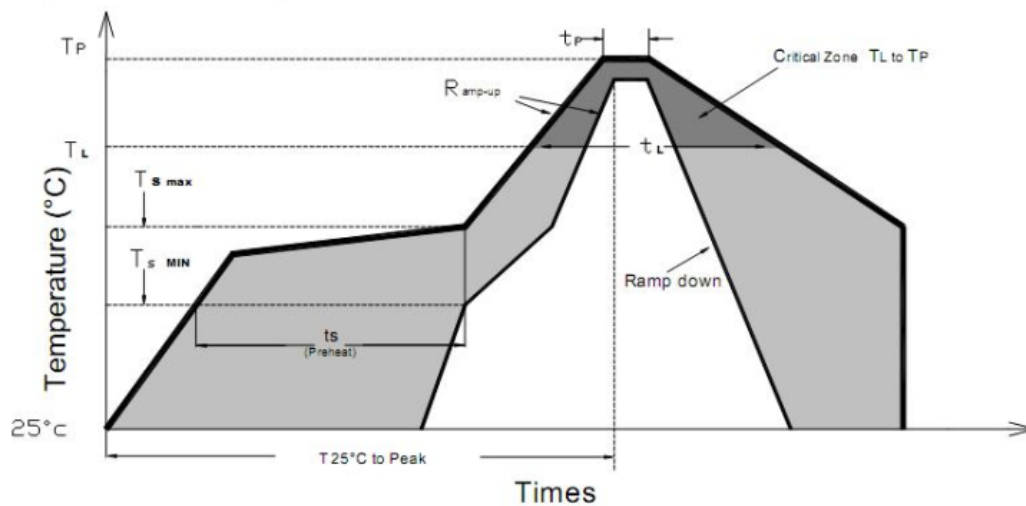
Profile Feature	Lead-Based Solder	Lead-Free Solder
Average Ramp-Up Rate (Ts max to Tp)	3 ℃/second max.	
Preheat: Temperature Min (Ts min)	100℃	150℃
Preheat: Temperature Min (Ts max)	150℃	200℃
Preheat: Time (ts min to ts max)	60-120 seconds	60-180 seconds
Time Maintained Above: Temperature (T L)	183 ℃	217 ℃
Time Maintained Above: Time (t L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature (T P)	215 ℃	238 ℃
Time Within 5℃ ℃ of Actual Peak Temperature (tp)	<10 seconds	<10 seconds
Ramp-Down Rate	6 ℃/second max	6 ℃/second max
Time 25 ℃ ℃ to Peak Temperature	<6 minutes max	<6 minutes max

Note: All temperatures refer to topside of the package, measured on the package body surface.

17.4. Anti-static and surge protection for IC devices

Static electricity and surges can damage the LED products of IC devices, so appropriate protective measures must be taken;

The signal input and output ports of IC devices must be connected in series with protective resistors to prevent product failure due to surge or electrostatic shock ports;
In order to protect the LED products of IC devices, whenever you encounter LEDs, wear anti-static straps, anti-static straps and anti-static gloves.

All devices and equipment must be grounded

It is recommended that each product be tested before shipment for relevant electrical tests to select defective products due to static electricity.
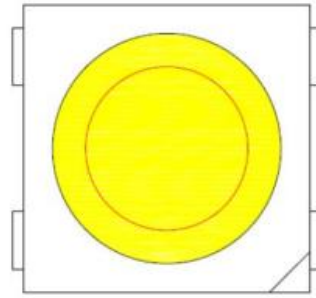
In the design of the circuit, consideration should be given to eliminating the surge to the LED

17.5 Other requirements

SMT nozzle requirements: (red circle refers to the inside diameter of the nozzle)
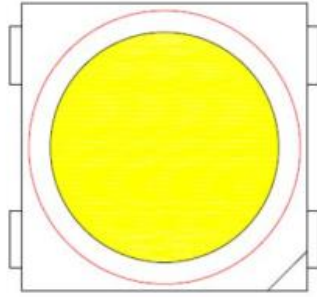

OK (the inside diameter of the nozzle is larger than the light-emitting area of the lamp)


NG (the inside diameter of the nozzle is smaller than the lighting area of the lamp)

Pressing the colloid surface will affect the reliability of LED because the LED is advanced silicone-gel.And therefore precautions should be taken to avoid the strong pressure on the component. It's proper to make the LED be used in safe condition when using a suction nozzle. Silicon packing with soft and elastic, it greatly reduces thermal stresses and unable to bear external mechanical forces. Therefore, preventive measures should be taken in process of manually handling.

① Clip the LED from its side.Neither directly touch the gel surface with the hand or sharp instrument, it may damage its internal circuit.
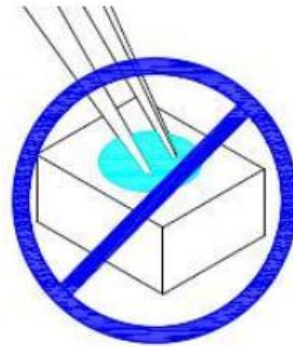
② Not to be double stacked, it may damage its internal circuit.
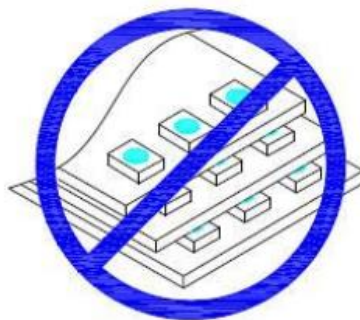
③   Can not be stored in or applied in the acidic sites of PH<7.